

Abstract

A probe assembly provides the capability to test integrated circuit ("IC") packages mounted onto ball grid arrays. The method comprises the step of first creating the lay out of the flexible attachment. Top and bottom rigid PC Boards are lain out and drilled. The drill creates holes that are the press fit diameter of nail pin. The holes are then plated with an annular ring on the outer exposed surface. The next step comprises laminating the flexible circuit between the two rigid PC Boards. Press fit nail pins are inserted through the holds in one side of the laminate sandwich until flush with the surface of the PC Board. Solder preforms are soldered the bottom surface of the laminate sandwich. The preforms mechanically and electrically attach the pins to the bottom rigid PC Board. A BGA socket can then be attached to the pins extending from the bottom of the laminated Flex-Rigid-Flex assembly.